

## Product Change Notice

Issue Date: December 21, 2018

**Change Type:**

Change internal die bump material to lead free.

**Parts Affected:**

BCM65100IFEBG  
BCM65100IFSBG  
BCM65112IFEBG  
BCM65112IFSBG  
BCM65116IFEBG  
BCM65116IFSBG  
BCM65118IFEBG  
BCM65118IFSBG  
BCM65118KFEBG  
BCM65300IFEB  
BCM65300IFEBG  
BCM65300IFSBG  
BCM65308IFEBG

**Description and Extent of Change:**

Change internal die bump material to lead free.

**Reasons for Change:**

Enables BCM651xx/BCM653xx family of parts to be ROHS 6/6.

**Effect of Change on Fit, Form, Function, Quality, or Reliability:**

No change on Fit, Form, Function, Quality, or Reliability.

**Effective Date of Change:**

Product shipments using this change will begin after 7/1/2019, but may change. Timing of shipment of the changed part will vary by part number depending on customer demand and inventory levels.

**Qualification Data:**

Data is expected to be available by 4/1/19.

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Please contact your Broadcom Inc. field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.